

# ANTREX Electronics

## Electronic Components Sourcing Information

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### Product Reference Information

|                      |                                                |
|----------------------|------------------------------------------------|
| <b>Part Number:</b>  | V2FM12-M3/I                                    |
| <b>Manufacturer:</b> | Vishay General Semiconductor - Diodes Division |
| <b>Package:</b>      | DO-219AB                                       |
| <b>Availability:</b> | Please confirm with sales                      |

#### Product Page:

<https://antrexco.com/product/details/vishay-general-semiconductor-diodes-division/v2fm12-m3-i.html>



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New & Original Components

Supplier verification and packaging condition review

CoC / RoHS / REACH documents available on request

Secure sourcing support for OEM / EMS projects

#### Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.

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# Surface-Mount TMBS<sup>®</sup> (Trench MOS Barrier Schottky) Rectifiers

## eSMP<sup>®</sup> Series



Top view

Bottom view

### SMF (DO-219AB)

Cathode  Anode

## LINKS TO ADDITIONAL RESOURCES



3D Models

## PRIMARY CHARACTERISTICS

|                                        |                |
|----------------------------------------|----------------|
| $I_{F(AV)}$                            | 2.0 A          |
| $V_{RRM}$                              | 120 V          |
| $I_{FSM}$                              | 40 A           |
| $V_F$ at $I_F = 2$ A ( $T_A = 125$ °C) | 0.65 V         |
| $T_J$ max.                             | 175 °C         |
| Package                                | SMF (DO-219AB) |
| Circuit configuration                  | Single         |

## FEATURES

- Trench MOS Schottky technology
- Low profile package
- Ideal for automated placement
- Low forward voltage drop, low power losses
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Wave and reflow solderable
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Compatible to SOD-123W package case outline
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## TYPICAL APPLICATIONS

For use in high frequency inverters, freewheeling, DC/DC converters, and polarity protection in commercial, industrial, and automotive applications.

## MECHANICAL DATA

### Case: SMF (DO-219AB)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

**Polarity:** color band denotes the cathode end

## MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)

| PARAMETER                                                                          | SYMBOL                     | V2FM12      | UNIT |
|------------------------------------------------------------------------------------|----------------------------|-------------|------|
| Device marking code                                                                |                            | 2MS         |      |
| Maximum repetitive peak reverse voltage                                            | $V_{RRM}$                  | 120         | V    |
| Maximum average forward rectified current (fig.1)                                  | $I_{F(AV)}$ <sup>(1)</sup> | 2.0         | A    |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | $I_{FSM}$                  | 40          | A    |
| Operating junction temperature range                                               | $T_J$ <sup>(2)</sup>       | -40 to +175 | °C   |
| Storage temperature range                                                          | $T_{STG}$                  | -55 to +175 |      |

## Notes

<sup>(1)</sup> Free air, mounted on FR4 PCB, 2 oz. standard footprint

<sup>(2)</sup> The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$

**ELECTRICAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

| PARAMETER                     | TEST CONDITIONS        |                         | SYMBOL                        | TYP. | MAX. | UNIT |
|-------------------------------|------------------------|-------------------------|-------------------------------|------|------|------|
| Instantaneous forward voltage | I <sub>F</sub> = 1.0 A | T <sub>A</sub> = 25 °C  | V <sub>F</sub> <sup>(1)</sup> | 0.68 | -    | V    |
|                               | I <sub>F</sub> = 2.0 A |                         |                               | 0.86 | 0.96 |      |
|                               | I <sub>F</sub> = 1.0 A | T <sub>A</sub> = 125 °C |                               | 0.56 | -    |      |
|                               | I <sub>F</sub> = 2.0 A |                         |                               | 0.65 | 0.73 |      |
| Reverse current               | V <sub>R</sub> = 90 V  | T <sub>A</sub> = 25 °C  | I <sub>R</sub> <sup>(2)</sup> | 0.3  | -    | μA   |
|                               |                        | T <sub>A</sub> = 125 °C |                               | 200  | -    |      |
|                               | V <sub>R</sub> = 120 V | T <sub>A</sub> = 25 °C  |                               | -    | 65   |      |
|                               |                        | T <sub>A</sub> = 125 °C |                               | 350  | 2000 |      |
| Typical junction capacitance  | 4.0 V, 1 MHz           |                         | C <sub>J</sub>                | 130  | -    | pF   |

**Notes**(1) Pulse test: 300  $\mu\text{s}$  pulse width, 1 % duty cycle(2) Pulse test: Pulse width  $\leq 5\text{ ms}$ **THERMAL CHARACTERISTICS** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)

| PARAMETER                  | SYMBOL                   | V2FM12 | UNIT                 |
|----------------------------|--------------------------|--------|----------------------|
| Typical thermal resistance | $R_{\theta JA}^{(1)(2)}$ | 125    | $^{\circ}\text{C/W}$ |
|                            | $R_{\theta JM}^{(2)}$    | 26     |                      |

**Notes**(1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ (2) Device mounted on FR4 PCB, 2 oz. standard footprint, thermal resistance  $R_{\theta JA}$  – junction-to-ambient; thermal resistance  $R_{\theta JM}$  – junction-to-mount**ORDERING INFORMATION** (Example)

| PREFERRED P/N              | UNIT WEIGHT (g) | PREFERRED PACKAGE CODE | BASE QUANTITY | DELIVERY MODE                      |
|----------------------------|-----------------|------------------------|---------------|------------------------------------|
| V2FM12-M3/H                | 0.015           | H                      | 3000          | 7" diameter plastic tape and reel  |
| V2FM12-M3/I                | 0.015           | I                      | 10 000        | 13" diameter plastic tape and reel |
| V2FM12HM3/H <sup>(1)</sup> | 0.015           | H                      | 3000          | 7" diameter plastic tape and reel  |
| V2FM12HM3/I <sup>(1)</sup> | 0.015           | I                      | 10 000        | 13" diameter plastic tape and reel |

**Note**

(1) AEC-Q101 qualified

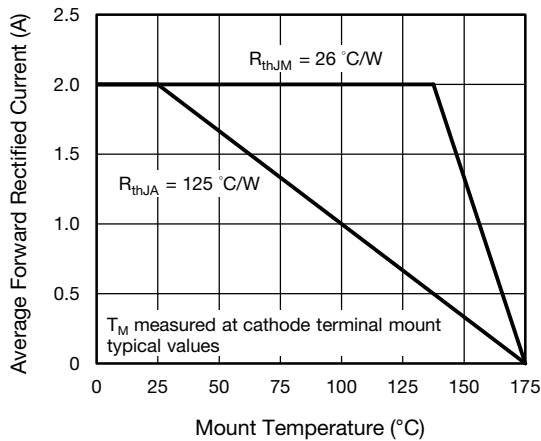
**RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25\text{ }^{\circ}\text{C}$  unless otherwise noted)


Fig. 1 - Maximum Forward Current Derating Curve

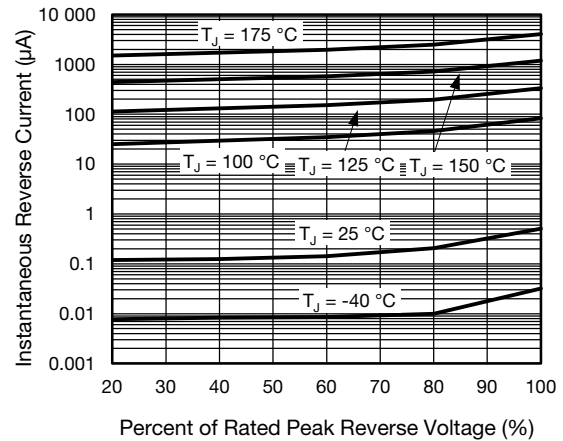


Fig. 4 - Typical Reverse Leakage Characteristics

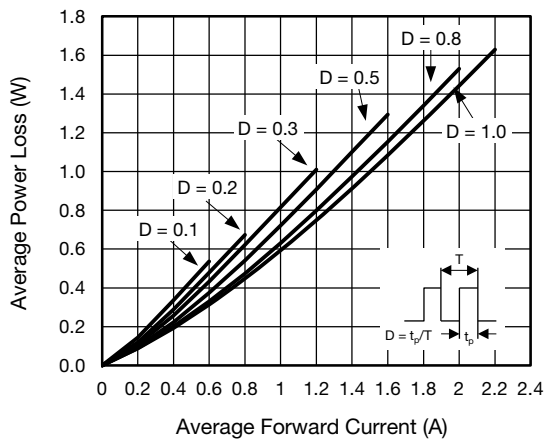


Fig. 2 - Average Power Loss Characteristics

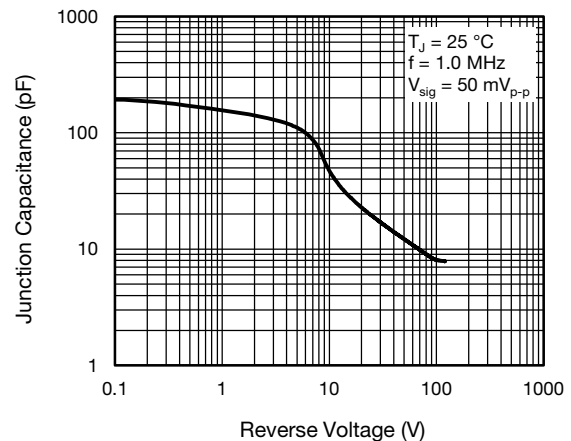


Fig. 5 - Typical Junction Capacitance

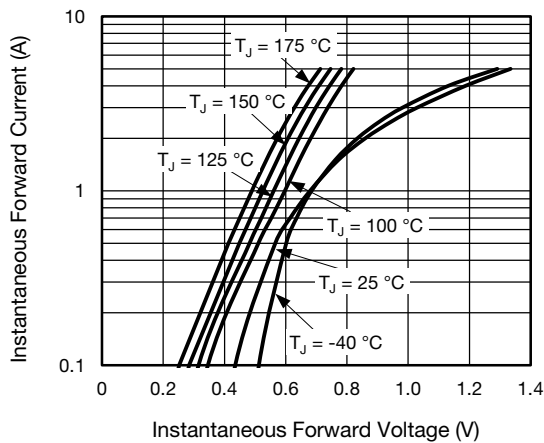


Fig. 3 - Typical Instantaneous Forward Characteristics

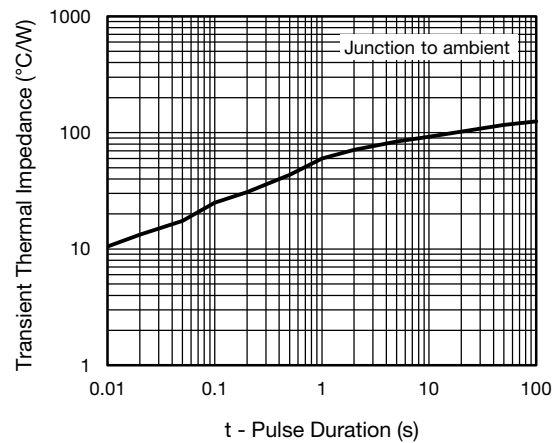
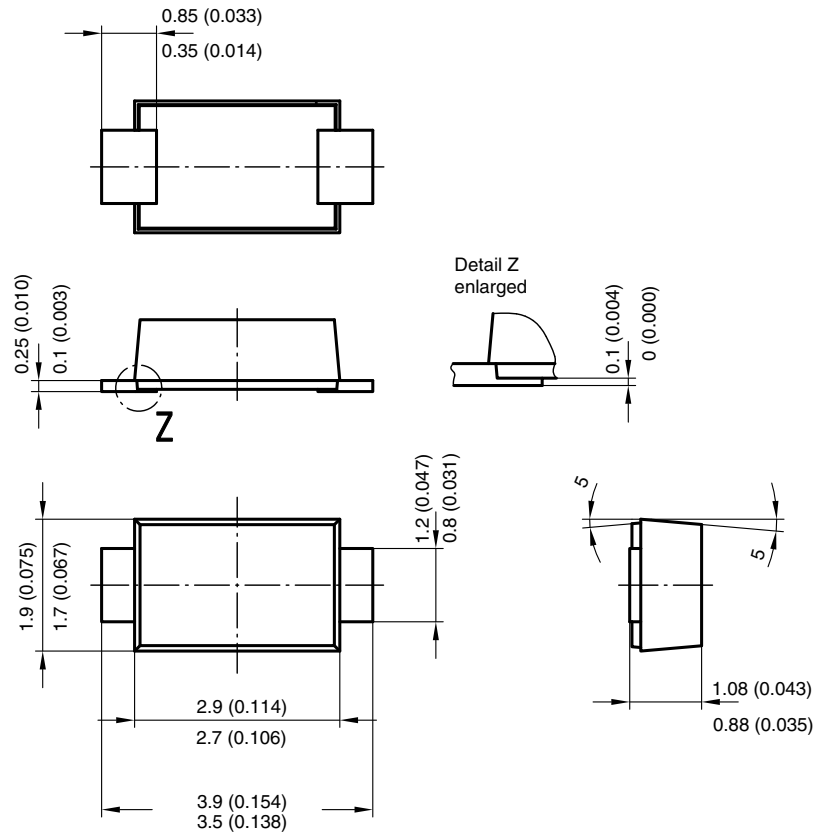
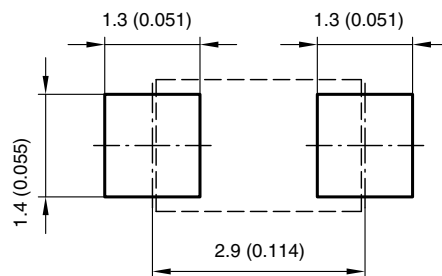


Fig. 6 - Typical Transient Thermal Impedance

**PACKAGE OUTLINE DIMENSIONS** in millimeters (inches)


Foot print recommendation:



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